



Physical Interface & Carriers Japan TC Chapter

Japan Standards Autumn Meetings 2024

September 2, 2024

Official Virtual TC Chapter Meeting & SEMI Japan office room1 [Hybrid]

13:00-15:00 JST

AGENDA

1.0 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)

1.3 Agenda Review

2.0 Review of Previous Meeting Minutes

3.0 Liaison Report

3.1 North America

4.0 Staff Report

5.0 Ballot Review: None

6.0 Subcommittee & Task Force Reports

6.1 Global PIC Standards Maintenance TF

6.2 Japan Electron Microscopy Workflow liaison TF

6.3 Panel Level Packaging Panel FOUP TF

6.4 Next Gen Assembly / Test Material Handling TF

6.5 Liaison: 3D Packaging & Integration JA TCC] Panel Level Packaging Glass Carrier TF

6.6 [Liaison: 3D Packaging & Integration NA TCC] Panel Level Packaging Panel TF

7.0 Old Business

None

8.0 New Business

8.1 Project Period Review:

8.2 5-Year Review

8.3 SEMICON Japan Schedule (TC & Task Force)

9.0 Action Item Review

10.0 Next Meeting and Adjournment

9:00-12:00, December 12, 2024 at Room702 7F Int'l Conference Tower, Tokyo Big Sight + OVTCCM during SEMICON Japan 2024